

### Description

Yantel's surface mount catalog bandpass filters utilize Yantel's low loss temperature stable materials which offer small size and minimal performance variation over temperature. The catalog BPF's are offered in a variety of frequency bands, which offers a drop in solution with highly repeatable performance.

### Features

- Small Size
- Fully Shielded Component
- Solder Surface Mount Package
- Moisture Sensitivity Level: MSL1
- Frequency Stable over Temperature
- Operating & Storage Temp: -55°C to +125°C
- Characteristic Impedance: 50Ω

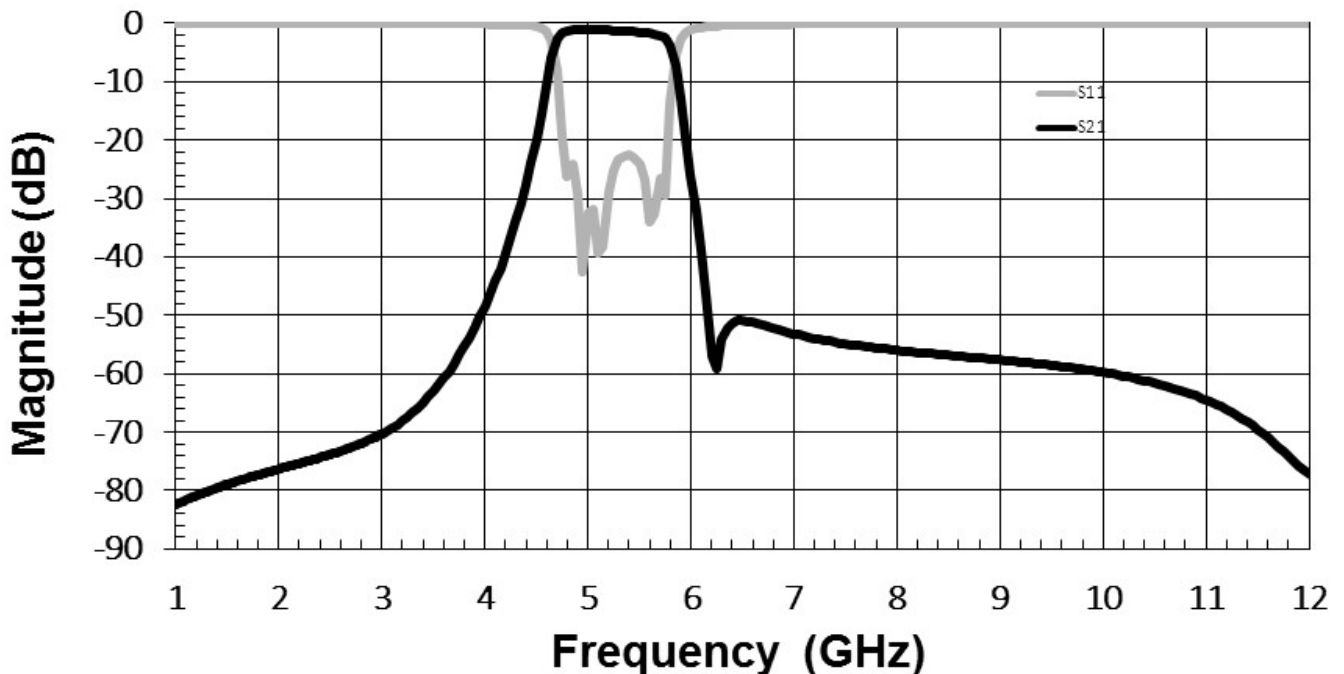
### Specifications\*

Parameter	Frequency Range (GHz)	Min	Typ.	Max
Insertion Loss (dB)	4.8 - 5.6		2.25	2.5
Return Loss (dB)			10.0	12.0
Low Side Rejection (dB)	DC - 3.5		40.0	45.0
High Side Rejection (dB)	6.2 - 12.5		40.0	45.0
CW Input Power** (W)				15
$\theta_{jc} \left( \frac{^{\circ}\text{C}}{\text{W}} \right)$	5			
Size (L x W x H)	8.89 x 5.08 x 2.50 mm			

\*Electrical specifications based on typical probed performance at room temperature. Insertion loss shall vary  $\pm 0.5$ dB over temperature.

\*\*Power rating assumes the component will be mounted to a PCB with good thermally conducting ground vias as outlined in the recommended PCB layout that are connected to an adequate heat sink. Max power is based on 125°C base temperature.

### Typical Measured Performance

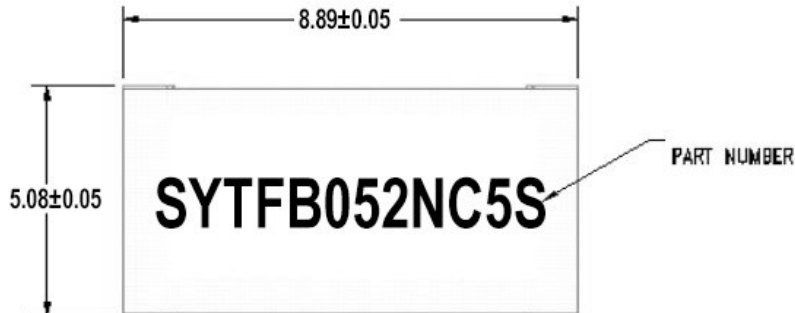


\*Typical de-embedded measured performance mounted on a connectorized test fixture. DEB is 0.254mm RO4350B with 50.00ohm CPW ground traces going into the ports at room temperature.

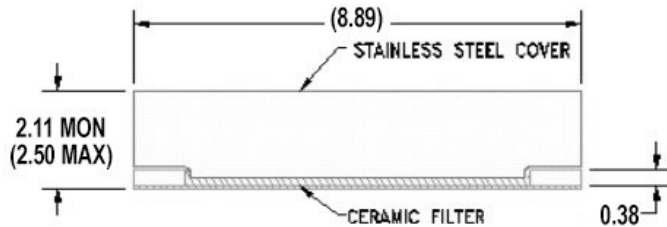
### Physical Dimensions

Units = mm

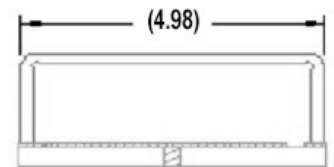
#### Top View



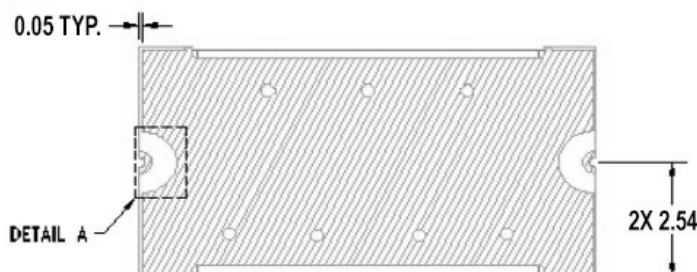
#### Side View



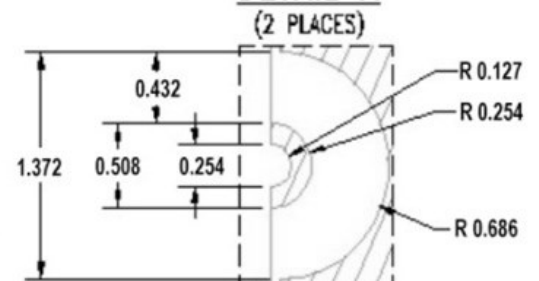
#### End View



#### Bottom View



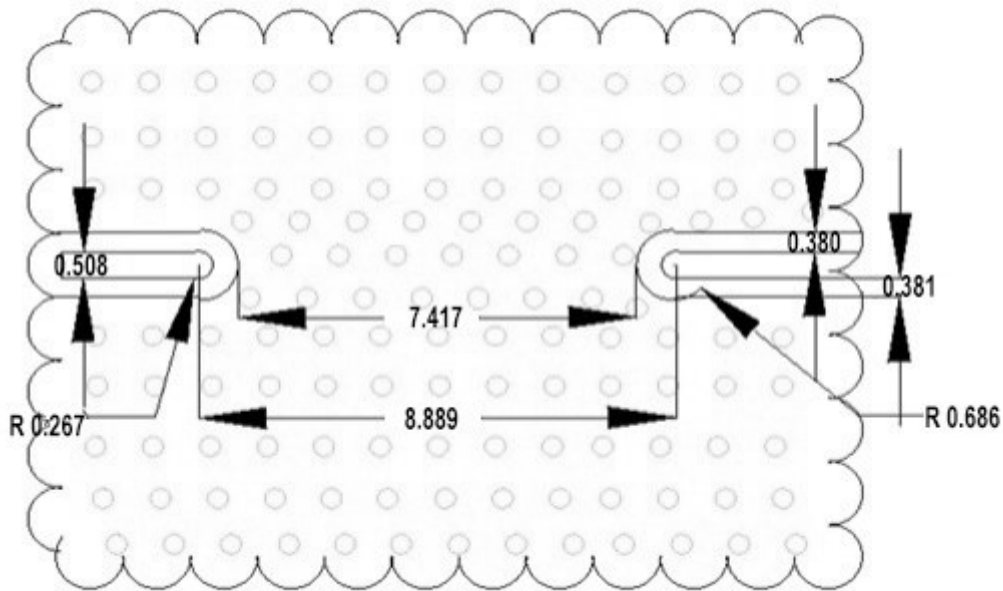
#### DETAIL A



#### Notes :

1. Termination Finish:  
ENIG: 76-152  $\mu\text{m}$  Au over 1270  $\mu\text{m}$  Ni
2. Maximum Assembly Process Temperature: 250°C
3. Dimension tolerance:  $\pm 0.05$

## Recommended PCB Layout



Units = mm

### Note:

- 50 $\Omega$  trace dimensions are application specific.
- Ensure adequate grounding beneath the part.